

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5320219

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
OSAMU WATANABE	12/05/2018
TOMONORI NAKAMURA	12/05/2018
YOSHIHITO HAGIWARA	11/26/2018
YUJI KANAI	11/14/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SHINKAWA LTD.
<b>Street Address:</b>	51-1, INADAIRA 2-CHOME, MUSASHIMURAYAMA-SHI,
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	208-8585
<b>Name:</b>	VALQUA, LTD.
<b>Street Address:</b>	1-1, OSAKI 2-CHOME, SHINAGAWA-KU,
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	141-6024
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16305393
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(949)391-4699
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	886223692800
<b>Email:</b>	USA@JCIPGroup.com
<b>Correspondent Name:</b>	JCIPRNET
<b>Address Line 1:</b>	P.O. BOX 600 TAIPEI GUTING
<b>Address Line 4:</b>	TAIPEI CITY, TAIWAN 10099
<b>ATTORNEY DOCKET NUMBER:</b>	82847-US-1215-PCT
<b>NAME OF SUBMITTER:</b>	BELINDA LEE

<b>SIGNATURE:</b>	/Belinda Lee/
<b>DATE SIGNED:</b>	01/11/2019
<b>Total Attachments: 6</b> source=82847_assgn#page1.tif source=82847_assgn#page2.tif source=82847_assgn#page3.tif source=82847_assgn#page4.tif source=82847_assgn#page5.tif source=82847_assgn#page6.tif	

## ASSIGNMENT

WHEREAS,

- |                       |                      |
|-----------------------|----------------------|
| 1. Osamu WATANABE     | 2. Tomonori NAKAMURA |
| 3. Yoshihito HAGIWARA | 4. Yuji KANAI        |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD OF MOUNTING DIE**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, **1. SHINKAWA LTD.**

of 51-1, Inadaira 2-chome, Musashimurayama-shi, Tokyo, 208-8585, Japan

**2. VALQUA, LTD.**

of 1-1, Osaki 2-chome, Shinagawa-ku, Tokyo, 141-6024, Japan

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

## ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Osamu Watanabe  
Sole or First Joint Inventor: Osamu WATANABE

Date: 5th, 12, 2018

Signature: Tomonori Nakamura  
Second Joint Inventor: Tomonori NAKAMURA

Date: 5th-12-2018

Signature: \_\_\_\_\_  
Third Joint Inventor: Yoshihito HAGIWARA

Date: \_\_\_\_\_

Signature: \_\_\_\_\_  
Fourth Joint Inventor: Yuji KANAI

Date: \_\_\_\_\_

## ASSIGNMENT

WHEREAS,

- |                       |                      |
|-----------------------|----------------------|
| 1. Osamu WATANABE     | 2. Tomonori NAKAMURA |
| 3. Yoshihito HAGIWARA | 4. Yuji KANAI        |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD OF MOUNTING DIE**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, **1. SHINKAWA LTD.**

of 51-1, Inadaira 2-chome, Musashimurayama-shi, Tokyo, 208-8585, Japan

**2. VALQUA, LTD.**

of 1-1, Osaki 2-chome, Shinagawa-ku, Tokyo, 141-6024, Japan

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

## ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Sole or First Joint Inventor: Osamu WATANABE

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Second Joint Inventor: Tomonori NAKAMURA

Signature: YOSHIHITO HAGIWARA

Date: 2018.11.26

Third Joint Inventor: Yoshihito HAGIWARA

Signature: \_\_\_\_\_

Date: \_\_\_\_\_

Fourth Joint Inventor: Yuji KANA

US

## ASSIGNMENT

WHEREAS,

- |                       |                      |
|-----------------------|----------------------|
| 1. Osamu WATANABE     | 2. Tomonori NAKAMURA |
| 3. Yoshihito HAGIWARA | 4. Yuji KANAI        |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **METHOD OF MOUNTING DIE**

[ ] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, **1. SHINKAWA LTD.**

of 51-1, Inadaira 2-chome, Musashimurayama-shi, Tokyo, 208-8585, Japan

**2. VALQUA, LTD.**

of 1-1, Osaki 2-chome, Shinagawa-ku, Tokyo, 141-6024, Japan

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

## ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: \_\_\_\_\_  
Sole or First Joint Inventor: Osamu WATANABE

Date: \_\_\_\_\_

Signature: \_\_\_\_\_  
Second Joint Inventor: Tomonori NAKAMURA

Date: \_\_\_\_\_

Signature: \_\_\_\_\_  
Third Joint Inventor: Yoshihito HAGIWARA

Date: \_\_\_\_\_

Signature: yuji kanaï  
Fourth Joint Inventor: Yuji KANAI

Date: 11 / 14 / 2018